3D Packaging and Integration Japan TC Chapter

Meeting Summary and Minutes

Japan Standards Spring Meetings 2025
Monday, May 19, 2025 2:00 PM – 4:00 PM JST
SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

TC Chapter Announcements

Next TC Chapter Meeting

Monday, October 6, 2025 2:00 PM – 4:00 PM JST

SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Kazunori Kato (AiT), Masahiro Tsuriya (iNEMI), Haruo Shimamoto (AIST)
SEMI Staff: Akiko Yoshida (SEMI Japan)

Company	*Last*	*First*	*Company*	*Last*	*First*
AIST	*Shimamoto*	*Haruo*	*NAURA*	*Cao*	*Clark*
AiT	*Kato*	*Kazunori*	Shin-Etsu Polymer	Odashima	Satoshi
AT&S	*Luo*	*Rowling*	*Yokohama National University*	*Sano*	*Marie*
EV Group Japan	*Kurotaki*	*Hirokazu*	*Self*	*Takahashi*	*Mark*
iNEMI	*Tsuriya*	*Masahiro*	*Suss Microtech Solutions Gmbh*	*Muller*	*Philpppe*
ITRI	*Lo*	*Wei-Chung*			
Japan Display	Watanabe	Ryoichi	SEMI Japan	Koga	Nahoko
Kanagawa Institute of Advanced Industria and Technology	*Nemoto*	*Shunsuke*	SEMI Japan	Yoshida	Akiko

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
None		

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
None	

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
None		

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

Document #	*Document Title*	*ISC A&R Action*	*A&R Forms*
None			

#1 **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

#2 **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
None			

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
7359	SNARF	3D Packaging & Integration 5-Year Review TF	Reapproval of SEMI G11-0519, Practice for RAM Follower Gel Time and Spiral Flow of Thermal Setting Molding Compounds
7360	SNARF	3D Packaging & Integration 5-Year Review TF	Reapproval of SEMI G73-0519, Test Method for Pull Strength for Wire Bonding
7361	SNARF	3D Packaging & Integration 5-Year Review TF	Reapproval of SEMI G77-0699 (Reapproved 1020), Specification for Frame Cassette for 300 mm Wafers

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:
http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
7359	Cycle 6, 2025	3D Packaging & Integration 5-Year Review TF	Reapproval of SEMI G11-0519, Practice for RAM Follower Gel Time and Spiral Flow of Thermal Setting Molding Compounds
7360	Cycle 6, 2025	3D Packaging & Integration 5-Year Review TF	Reapproval of SEMI G73-0519, Test Method for Pull Strength for Wire Bonding
7361	Cycle 6, 2025	3D Packaging & Integration 5-Year Review TF	Reapproval of SEMI G77-0699 (Reapproved 1020), Specification for Frame Cassette for 300 mm Wafers

Table 9 SNARF(s) Granted a One-Year Extension

#	*TF*	*Title*	*Expiration Date*
None			

Table 10 SNARF(s) Cancelled

#	*TF*	*Title*	*Expiration Date*
None			

Table 11 Standard(s) to receive Inactive Status

Standard Designation	*Title*
SEMI G52-1120	Test Method for Measurement of Ionic Contamination on Semiconductor Leadframes
SEMI G92-0315 (Reapproved 1220)	Specification for Tape Frame Cassette for 450 mm Wafer

Table 12 New Action Items

Item #	*Assigned to*	*Details*
3DP&I_20250519-01	SEMI Staff/ 5-Year Review TF	To submit SEMI G11, G73, and G77 Reapproval Ballots for Cycle 6, 2025.
3DP&I_20250519-02	SEMI Staff	To inform SEMI Standards Publication Staff to make SEMI G52 and G92 "Inactive."
3DP&I_20250519-03	5-Year Review TF	To prepare Line Item/ Major Revision SNARFs for SEMI G74 and G87.
3DP&I_20250519-04	5-Year Review TF	To prepare Line Item Revision SNARFs for SEMI G82 and G95.
3DP&I_20250519-01	SEMI Staff/ 5-Year Review TF	To submit SEMI G11, G73, and G77 Reapproval Ballots for Cycle 6, 2025.

Table 13 Previous Meeting Action Items

Item #	*Assigned to*	*Details*
3DP&I_20250203-01	SEMI Staff	To forward the result of ballot review for Doc.#7300 to the ISC A&R SC for procedural review. →Closed
3DP&I_20250203-02	SEMI Staff/ 5-Year Review TF	To check all the documents listed for 5-year review whether they are compliant with Style Manual. →Closed

1 Welcome, Reminders, and Introductions

Kazunori Kato (AiT) called the meeting to order at 14:00. The meeting reminders on antitrust issues, intellectual property issues, and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01_Required Meeting Elements March 2024_J

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the minutes as written.
By / 2nd:	Haruo Shimamoto (AIST)/ Satoshi Odashima (Shin-Etsu Polymer)
Discussion:	None.
Vote:	10-Y 0-N. Motion passed.

Attachment: 02_3DP&I_JA_Minutes_20250204_R0

3 Liaison Reports

3.1 *Japan Regional Standards Committee (JRSC)*

Akiko Yoshida (SEMI Japan) reported for the JRSC that the meeting was held on Thursday, April 17. Topics that are relevant to the 3D Packaging and Integration Japan TC Chapter were:

- The ISC Regulations SC recommended to postpone enforcement of implementation of use of Connect@SEMI by all the TFs until next Regs/ PM revision (which is currently aimed to become effective by SEMICON West in October).
- The Planning Meeting will be held on Thursday, August 28, inviting all the TF leaders as well as TC co-chairs to deepen knowledge related to standardization. More details will be provided as soon as they are finalized.

3.2 *Global Coordinating Subcommittee (GCS)*

Akiko Yoshida (SEMI Japan) reported for the GCS that there was no GCS discussion or voting between Japan TC Chapter meetings.

3.3 *3D Packaging and Integration North America TC Chapter*

Akiko Yoshida (SEMI Japan) reported for the 3D Packaging and Integration North America TC Chapter. Of note.

- Last meeting was held on Thursday, February 27, 2025 during NA Winter Meetings and next meeting will be held on Thursday, June 5, 2025 during NA Summer Meetings at SEMI HQ in Milpitas.
- SNARF 7331, New Standard: Guide for Peel Testing of RDLs and Other Traces Used within HDI, WLP, and PLPs Structures, proposed by the 3DP&I Inspection & Metrology TF was approved by the GCS on January 31, 2025.
- Doc.#7307, Reapproval of SEMI 3D22-1219, Guide on Measurements of Openings and Vias in Glass passed TC Chapter review as balloted.
- SNARF 7337, Reapproval of SEMI 3D9-0914 (Reapproved 0420), Guide for Describing Materials Properties for a 300 mm 3D-IC Wafer Stack, SNARF 7338, Reapproval of SEMI 3D10-0814 (Reapproved 0420), Guide to Describing Materials Properties for Intermediate Wafers for Use in a 300 mm 3DS-IC Wafer Stack, and SNARF 7339, Reapproval of SEMI 3D11-1214 (Reapproved 0420), Terminology for Through Glass Via in Glass Geometrical Metrology were approved and their Letter Ballot submissions for Cycle 3 or 4, 2025 were authorized.

Attachment: 03_NA 3DP&I Liaison Report Feb2025 v1

Staff Note: The liaison report file was not sent to the Japan TC Chapter on the day of the TC Chapter meeting, but it was obtained afterwards and attached to the meeting minutes.

3.4 *3D Packaging and Integration Taiwan TC Chapter*

Akiko Yoshida (SEMI Japan) reported for the 3D Packaging and Integration Taiwan TC Chapter that the TC Chapter meeting has not been held since September 2, 2022.

4 SEMI Staff Report

Akiko Yoshida (SEMI Japan) gave the SEMI Staff Report. Of notes:

- SEMICON West 2025 will be held in Phoenix, Arizona in October. The venue of SEMICON West will alternate between Phoenix and San Francisco every October thereafter.
- By Feb 2025, all Standards Task Forces shall use Connect@SEMI to host documents that are currently in development. However, the ISC Regulations SC recommended to postpone enforcement of implementation until next Regs/ PM revision (which is currently aimed to become effective by NA Summer meeting in June). The Regs SC is working with SEMI to update both Connect@SEMI and rules so that they are aligned each other.
- SEMI University Japan Store launched in June, 2024, which proves SEMI Japan original e-learning courses with Japanese audio or subtitles including SEMI Standards tutorials.

Attachment: 04_Staff Report Feb 2025 v2_ay

5 Ballot Review

None.

6 Subcommittee and Task Force Reports

6.1 *3DS IC Bonded Layer Inspection Metrology Task Force*

Haruo Shimamoto (AIST) reported for the 3DS IC Bonded Layer Inspection Metrology Task Force. The TF met in April and had discussion on the details of Doc.#7299, New Standard: Guide for 3DIS IC Bonded Layer Inspection Metrology. They would work further to complete drafting the document. The TF plans to present the ballot-ready draft at the next TC Chapter meeting.

6.2 *Wafer Bond Strength Measurement by Double-cantilever Beam Task Force*

Marie Sano (Yokohama National University) reported for the Wafer Bond Strength Measurement by Double-cantilever Beam Task Force. Not much progress has been made, but the TF is drafting the document. The next TF meeting will be held in Summer.

6.3 *3D Packaging & Integration 5-Year Review Task Force*

Masahiro Tsuriya (iNEMI) reported for the 3D Packaging and Integration 5-year Review TF. The TF reviewed all documents which require 5-year review in 2025 and recommended the course of actions (refer to the attachment).

- The TC Chapter decided to make the following documents “Inactive.”
    - SEMI G52-1120, Test Method for Measurement of Ionic Contamination on Semiconductor Leadframes
    - SEMI G92-0315 (Reapproved 1220), Specification for Tape Frame Cassette for 450 mm Wafer
- The TC Chapter approved the below Reapproval SNARFs and authorized their Letter Ballot submissions for Cycle 6, 2025.

Motion:	Approve SNARFs for Reapproval of SEMI G11-0519, Practice for RAM Follower Gel Time and Spiral Flow of Thermal Setting Molding Compounds, SEMI G73-0519, Test Method for Pull Strength for Wire Bonding, and SEMI G77-0699 (Reapproved 1020), Specification for Frame Cassette for 300 mm Wafers.
By / 2nd:	Masahiro Tsuriya (iNEMI)/ Satoshi Odashima (Shin-Etsu Polymer)
Discussion:	None.
Vote:	9-Y 0-N. Motion passed.

Motion:	Authorize the letter ballot submissions for Reapproval of SEMI G11-0519, Practice for RAM Follower Gel Time and Spiral Flow of Thermal Setting Molding Compounds, SEMI G73-0519, Test Method for Pull Strength for Wire Bonding, and SEMI G77-0699 (Reapproved 1020), Specification for Frame Cassette for 300 mm Wafers in Cycle 6, 2025.
By / 2nd:	Masahiro Tsuriya (iNEMI)/ Satoshi Odashima (Shin-Etsu Polymer)
Discussion:	None.
Vote:	9-Y 0-N. Motion passed.

- The TF will propose SNARFs at the next TC Chapter meeting for the below documents for editorial changes.
    - SEMI G82-1115 (Reapproved 1220), Specification for 300 mm Load Port for Frame Cassettes in Backend Process Editorial Change
    - SEMI G95-1120, Specification for Mechanical Features of 450 mm Load Port for Tape Frame Cassettes in the Backend Process Editorial Change
- The TF will work on updating the below documents. Haruo Shimamoto (AIST) explained the points to be revised in detail.
    - SEMI G74-0699 (Reapproved 1020), Specification for Tape Frame for 300 mm Wafers
    - SEMI G87-1108 (Reapproved 1020), Specification for Plastic Tape Frame for 300 mm Wafer Editorial Change

Attachment:	05_TF Report - 5yrs Review TF v2025_5
	06_SNARF_Sept2024_G11 Reapproval_R0
	07_SNARF_Sept2024_G73 Reapproval_R0
	08_SNARF_Sept2024_G77 Reapproval_R0

6.4 *3D Packaging & Integration Steering Group*

Masahiro Tsuriya (iNEMI) reported for the Steering Group. There has not been so much discussion in the Steering Group, but he said that the Steering Group is willing to have some discussion with SEMI SEA as well as the 3D Packaging and Integration Taiwan TC Chapter regarding related technology and standardization issues.

7 Old Business

7.1 *Project Period Review*

No SNARF will be expiring soon.

7.2 *Project Period Review*

Please refer to 6.3 for details.

8 New Business

8.1 *Program at SEMICON Japan 2025*

Kazunori Kato (AiT) said that TC co-chairs will discuss whether or not the TC Chapter will have a program at SEMICON Japan 2025. Akiko Yoshida (SEMI Japan) commented the contents should be fixed by the end of July if they wants to hold a program.

8.2 *Standardization of Pressure Measurement Film*

Kazunori Kato (AiT) shared that TC co-chairs and some companies had some discussion on possible standardization of pressure measurement film. A proposal to develop a new standard may be presented at the next TC Chapter meeting.

9 Action Item Review

9.1 *Open Action Items*

Item #	*Assigned to*	*Details*
3DP&I_20250203-01	SEMI Staff	To forward the result of ballot review for Doc.#7300 to the ISC A&R SC for procedural review. →Closed
3DP&I_20250203-02	SEMI Staff/ 5-Year Review TF	To check all the documents listed for 5-year review whether they are compliant with Style Manual. →Closed

9.2 *New Action Items*

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3DP&I_20250519-03	5-Year Review TF	To prepare Line Item/ Major Revision SNARFs for SEMI G74 and G87.
3DP&I_20250519-04	5-Year Review TF	To prepare Line Item Revision SNARFs for SEMI G82 and G95.

10 Next Meeting and Adjournment

The next meeting is scheduled for Monday, October 6, 2025 2:00 PM – 4:00 PM JST via Official Virtual TC Chapter Meeting and at SEMI Japan Office, Tokyo, Japan (Hybrid). See http://www.semi.org/standards-events for the current list of events.

Adjournment: [16:00].

Respectfully submitted by:

Akiko Yoshida

Standards & EHS, SEMI Japan

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Email: ayoshida@semi.org

Minutes tentatively approved by:

Kazunori Kato (AiT), Co-chair	May 29, 2025
Masahiro Tsuriya (iNEMI), Co-chair	May 29, 2025
Haruo Shimamoto (AIST), Co-chair	June 1, 2025

Table 14 Index of Available Attachments[#1]

Title	*Title*
01_Required Meeting Elements March 2024_J	05_TF Report - 5yrs Review TF v2025_5
02_3DP&I_JA_Minutes_20250204_R0	06_SNARF_Sept2024_G11 Reapproval_R0
03_NA 3DP&I Liaison Report Feb2025 v1	07_SNARF_Sept2024_G73 Reapproval_R0
04_Staff Report Feb 2025 v2_ay	08_SNARF_Sept2024_G77 Reapproval_R0

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Akiko Yoshida at the contact information above.